



IPW/JB

PATENT APPLICATION

10551/489

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: J. Thomas WALKER

Application No.: 10/625,552

Examiner: DINH, TUAN T

Group Art Unit: 2841

Confirmation No. 8103

Filed: July 24, 2003

For: ATTACHABLE MODULAR ELECTRONIC SYSTEMS

INFORMATION DISCLOSURE STATEMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

03/11/2005 SDENR081 00000142 110600 10625552

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Sir:

Pursuant to 37 CFR § 1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom. The filing of this Information Disclosure Statement and the enclosed PTO Form No. 1449, shall not be construed as an admission that the information cited is prior art, or is considered to be material to patentability as defined in 37 C.F.R. § 1.56(b). The paragraphs marked below are applicable. It is believed that no fees other than those indicated below are due, but authorization is hereby given to charge any additional fees due, or to credit any overpayment, to deposit account 11-0600.

■ 1. This Information Disclosure Statement is being filed (a) within three months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. § 1.53(d), (b) within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, (c) before the mailing date of a first Office Action on the merits in the present application, OR (d) before the mailing of a first office action after filing of a request for continued examination. No certification or fee is required.

* 2. This Information Disclosure Statement is being filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a final action, Notice of Allowance, or any action that otherwise closes prosecution.

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Applicant: J. Thomas WALKER
Serial No. 10/625,552
IDS filed March 10, 2005

a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

b. I hereby certify that no item of information in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(2).

c. Please debit Deposit Account No. 11-0600 in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p) to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached. 37 CFR §1.97(c)(2).

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a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in any counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

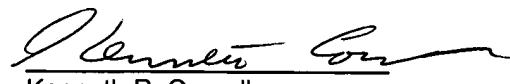
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Respectfully submitted,

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Date: March 10, 2005

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Application Number	10/625,552
Filing Date	July 24, 2003
First Named Inventor	J. Thomas WALKER
Art Unit	2841
Examiner Name	DINH, TUAN T
Attorney Docket Number	10551/489

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-6,297,564 B1	10-02-2001	Chung	
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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
		EP 0 948 813 B1	10-09-1997	Hans-Hermann Oppermann et al.		
		EP 0 933 010 B1	08-15-1997	Hugh P. Craig		
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		JP 63-220512	08-03-1990	Toshiba Corp		
		JP 03-246773	12/03/1993	Techno Sunstar		

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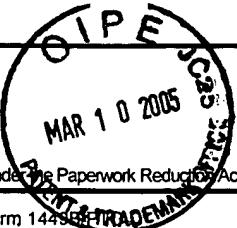
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NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"Theoretical and Experimental Aspects in the Depositing Process of Solder and Adhesive Pates in Surface Mount Technology," Alexandru Marin et al., IEEE Polytronic 2002 Conference, pp. 150-154.	
		"Isotropically Conductive Adhesives for High Power Electronics Applications," Kristian Olsson et al., IEEE Polytronic 2002 Conference, pp. 29-37.	
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		"Development of Fine Pitch (54μm) Flip Chip on Flex Interconnection Process," Jarmo Määttänen et al., IEEE Polytronic 2002 Conference, pp. 155-159.	
		"Microwave Cure of Conductive Adhesives for Flip-Chip & Microsystems Applications," G.P. Glinski et al., 2002 InterSociety Conference on Thermal Phenomena, pp. 848-853.	
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		"U.S. Demand for Electronic Polymer Products to Expand 6.4% Annually Through 2005," Adhesives & Sealants Industry, Vol. 9, Number 4, May 2002, p. 26.	

Examiner Signature

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		"Lead-Free Pastes Fail to Stick," <u>Adhesives Age</u> , Vol. 44, No. 9, September 2001, p. 9.	
		"Using Conductive Adhesives for Grounding Applications," Stanley Tead et al., 23rd-24th October 2000, Paper 115, Conference Paper, Charlotte, NC.	
		"More Secure Bonding for Fine Pitch Surface Mount Device Structural Elements," (English translation), by Thomas Gesang et al., Adhesion Kleben & Dichten, pp. 27-32, Nos. 7-8, 1998.	
		"Niche Applications Lift the Adhesives and Sealants Market," <u>Chemical Market Reporter</u> , May 21, 2001, Vol. 259, No. 21.	
		Jarmo Määttänen et al., "Development of Fine Pitch (54 µm) Flip Chip on Flex Interconnection Process," <u>IEEE Polytronic 2002 Conference</u> , pp. 155-159, 2002.	
		Rainer Möst, "Electronic Adhesives New Solutions for Short Cycled Manufacturing Process," <u>First International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics</u> , pp. 242-249, October 21-24, 2001.	
		Carl Yallop, "Conductive adhesives provide solution to electronic assembly problems," <u>European Design Engineer</u> , October 2001, pp. 50-51.	

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